

MPI CORPORATION

MPI Corporation

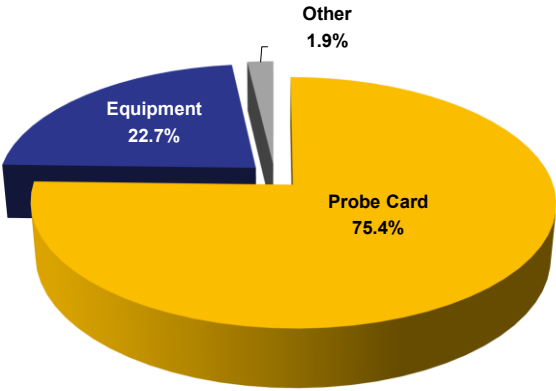
2025 Second Quarter Results

6223.TT

READY FOR THE TEST™

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Q225 Revenue Breakdown By Product



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## Consolidated Revenue 2025 vs. 2024

NT\$ 000			
	2025	2024	YoY
Q1	2,828,698	2,046,692	38.2%
Q2	3,292,785	2,392,994	37.6%
1H	6,121,483	4,439,686	37.9%

## Income Statement 2Q25 vs. 1Q25

NT\$ 000			
	2Q25	1Q25	QoQ
Net Revenue	3,292,785	2,828,698	16.4%
Gross profit	1,919,274	1,623,330	18.2%
Income from Operations	1,079,062	840,344	28.4%
Non-op. Income	-322,830	47,380	-781%
Pre-tax Income	756,232	887,724	-14.8%
Net Income	627,916	723,042	-13.1%
EPS	6.67	7.68	-13.1%

## Income Statement 2Q25 vs. 2Q24

NT\$ 000

	2Q25	2Q24	YoY
Net Revenue	3,292,785	2,392,994	37.6%
Gross profit	1,919,274	1,300,045	47.6%
Income from Operations	1,079,062	597,596	80.6%
Non-op. Income	-322,830	86,652	-473%
Pre-tax Income	756,232	684,248	10.5%
Net Income	627,916	542,674	15.7%
EPS	6.67	5.76	15.8%

## Income Statement 1H25 vs. 1H24

NT\$ 000

	1H25	1H24	YoY
Net Revenue	6,121,483	4,439,686	37.9%
Gross profit	3,542,604	2,325,937	52.3%
Income from Operations	1,919,406	984,371	95.0%
Non-op. Income	-275,450	182,224	-251%
Pre-tax Income	1,643,956	1,166,615	40.9%
Net Income	1,350,958	935,601	44.4%
EPS	14.35	9.94	44.4%

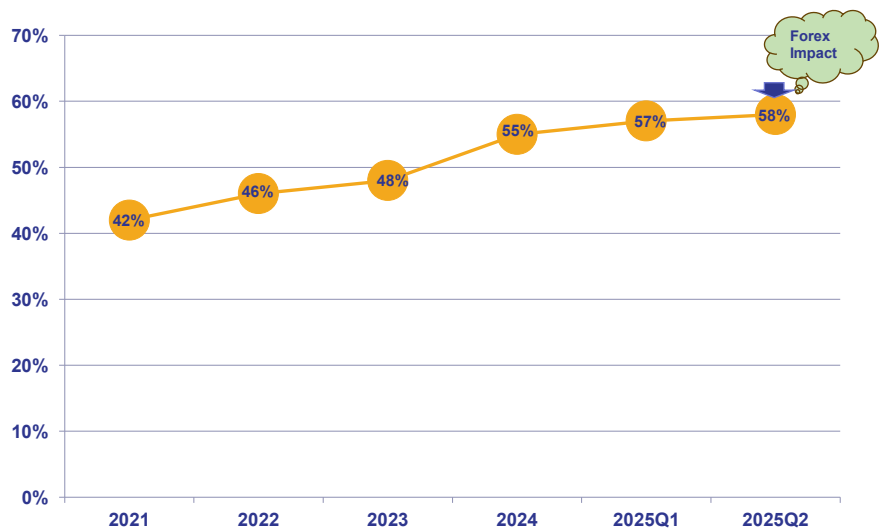
# Balance Sheet 1H25

	2025 1H		2024 1H	
				NT\$M
Cash and Cash Equivalents	5,637	28%	2,674	20%
Fixed Assets	8,620	43%	5,913	43%
Total Assets	20,123	100%	13,697	100%
LT Debt	1,152	6%	1,404	10%
Shareholders' Equity	9,393	47%	8,196	60%
EBITDA	1,644	27%	1,166	26%

\*EBITDA=operating income + depreciation & amortization expenses

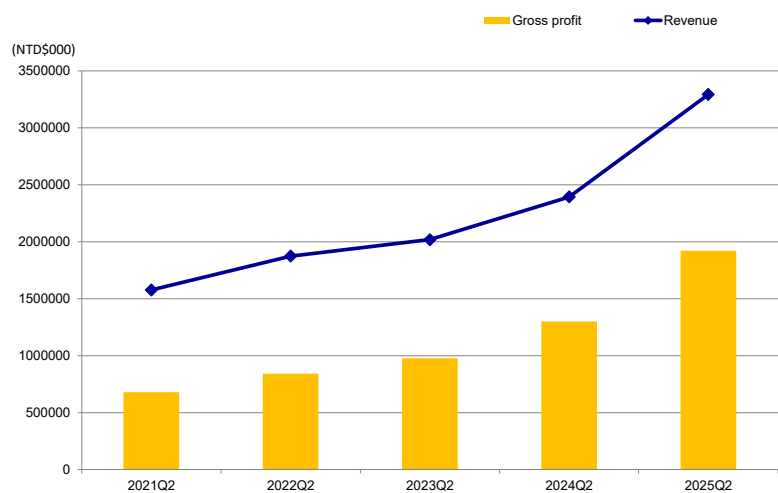
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# Gross Margin Performance



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# Historical 2Q Comparison for Past 5 YRs



MPIProbe Card

Advanced Wafer Sort Test Solutions

Vertical / MEMS

Cantilever

Features

Fine Pitch

MEMS

High Pin Count

High Speed

Substrate

Hand-wired

RF

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# MPI Photonics Automation

Wafer / Device Automated Probe, Test & Measurement, Sort and Inspection



**Sensing**



- High Power VCSEL Testing
- High Speed VCSEL Testing

**Communication**



- VCSEL / Photo-Detector Testing
- RF Character
- SiPh Die/PKG Platform

**Micro Display**



- uLED Mass Production Methodology
- Panel testing platform development

# MPI Thermal

Hot and Cold Air Flow  
Environmental Temperature Test

-100°C  +300°C

**ThermalAir Series**  
Temperature Testing Systems



Applications & Industry Segments

 Semiconductor
  Automotive
  Aerospace
  Telecommunications
  Fiber Optic
  Electronics
  Sensors
  Advanced Technology

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# MPI Advanced Semiconductor Test



Engineering Probe Systems  
and  
RF Probe Products

50 – 300 mm





26 – 110 GHz



Device Characterization



High Power



RF & mmW



Design Validation



Failure Analysis



Wafer Level Reliability



Silicon Photonics



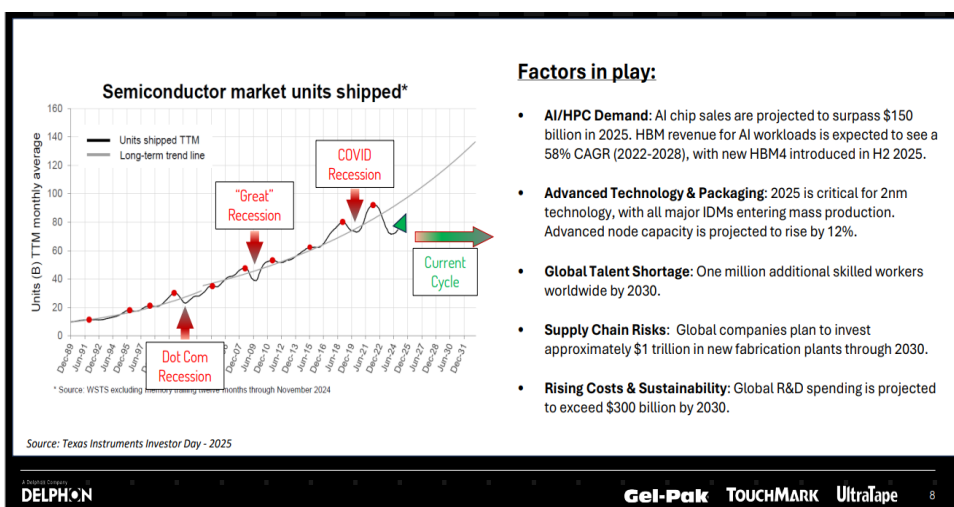
Laser Cutter

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## Semiconductor is Notoriously Cyclical



Source: "Increased Value of Wafer Test Innovation" by Jerry Broz, PhD

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# Rapid Technology Adoption | Rise of Generative AI



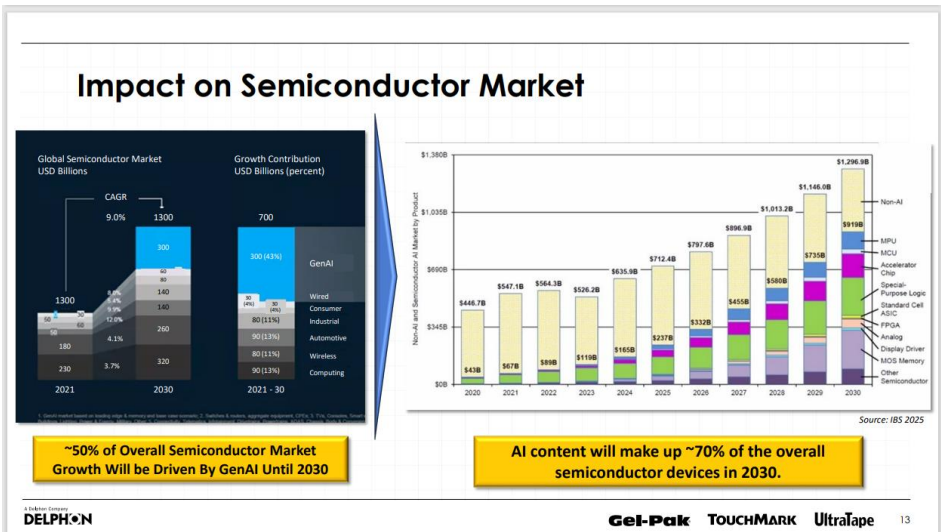
Source: N. Shahriari, IEEE ISCCC 2025

Source: J. Song, IEEE ISCCC 2025

Source: "Increased Value of Wafer Test Innovation" by Jerry Broz, PhD

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## Impact on Semiconductor Market

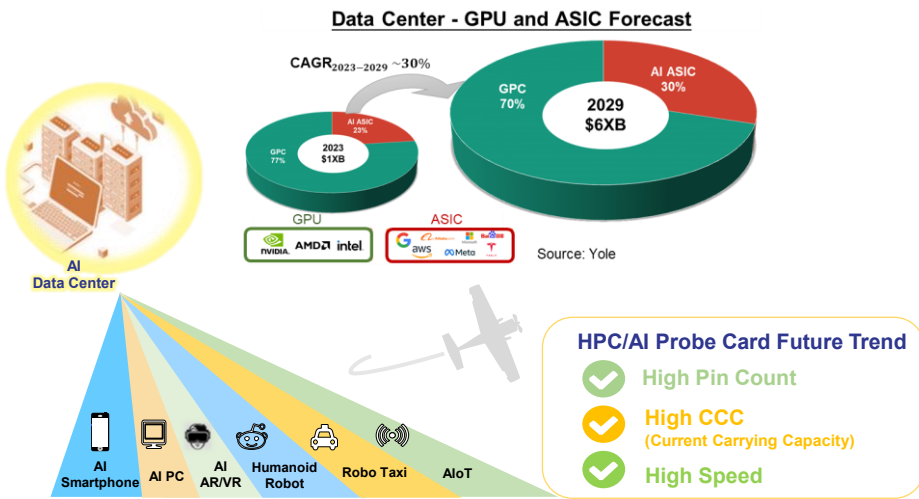


Source: "Increased Value of Wafer Test Innovation" by Jerry Broz, PhD

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# HPC/AI Probe Card Challenges



Source: TSMC

